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REVISION:	ECR/ECN INFORMATION:	TITLE: PRODUCT SPECIFICATION		SHEET No.	
D	EC No: UCP2009-2243	0.8r	nm PITCH VHDCI		1 of 12
D <u>DATE:</u> 3/12/2009		PLUG/RE	CEPTACLE ASSE	MBLY	
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	APPRO\	/ED BY:
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1.0 SCOPE

This specification covers the .8mm centerline VHDCI Plug and Receptacle assemblies.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND PART NUMBER <u>Product Name</u>

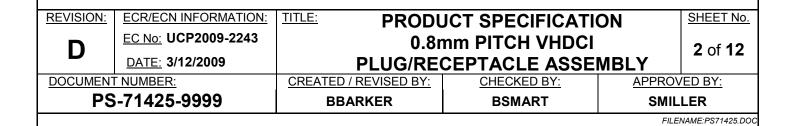
Product Name	Part Number
VHDCI PLUG KIT	71425 Series
RIGHT ANGLE RECEPTACLE ASSEMBLY	71430 Series
SMT RECEPTACLE ASSEMBLY	73776 Series
STACKED RECEPTACLE ASSEMBLY	74337 Series

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate Sales Drawings for information on dimensions, materials, plating and markings, recommended panel mounting procedures, and specifications.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

SD- 71430-003	Right Angle Receptacle Sales Drawing
PK-70873-0823	Right Angle Receptacle Packaging Specification
SD-73776-002	Vertical SMT Receptacle Sales Drawing
PK-70873-0824	Vertical SMT Receptacle Packaging Specification
MS-71425-0002	Plug Assembly Kit
PK-70873-0851	Plug packaging specification
EIA SP-3652, REV. O	Industry Standard for .8mm VHDCI Connector (Dated 31/07/97)
TS-71425-9999	Test Summary for VHDCI Plug assembly
SD-74337-003, -011, -003	Stacked Receptacle Sales Drawing
AS-71425-001	Wire Termination Specification – VHDCI Plug
PK-74337-001	Stacked Receptacle Packaging Drawing





14.0 RATINGS

- 4.1 VOLTAGE: 30 Volts AC (RMS)/DC
- 4.2 CURRENT: .5 Amps @ 50% Energized

4.3 TEMPERATURE:

- Operating: **55** °C to + **85** °C
- 4.4 UL/CSA CERTIFICATION:
 - 1. 71425, 71430, 73776 Series: UL file: E29179
 - 2. 71425, 71430, 73776 Series: CSA file: LR19980-520
 - 3. 74337 Series: UL file: 01NK13745
 - 4. 74337 Series: CSA file: 1194993

5.0 PERFORMANCE

5.1 ELECTRICAL PERFORMANCE:

Item	Test Condition	Requirement
5.1.1 Contact Resistance (Low Level) per EIA SP-3652, Rev.0	Mated Connectors with a maximum voltage of 20mV and a current of 100 mA.	50 milliohm Maximum Initial
5.1.2 Insulation Resistance per EIA 364, Test #21	Mated Connectors with a voltage of 100 VDC between adjacent terminals and between terminals and mounting panel.	500 Mega Ohms Minimum
5.1.3 Dielectric Withstanding Voltage per EIA 364, Test #20	Mated Connectors with a voltage of 250 VAC for 1 min. between adjacent terminals.	1 mA max leakage and no breakdown or flashover
5.1.4 Temperature Rise per EIA 364, Test #70	1.5 A max with 1 contact energized, 0.5 A max with 50% of the contacts energized, and 0.3 A max with 100% of the contacts energized.	Maximum Temperature Rise: 30°C, 10 milliohm change maximum
5.1.5 Shell Interface Resistance per EIA 364, Test #23	Mated connector shells with a maximum voltage of 20mV and a current of 100mA, between the ground leg of the receptacle shield and the solder tab of the plug shell.	50 milliohm Maximum Initial

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5.2 MECHANICAL PERFORMANCE:

Item	Test Condition	Requireme	nt	
5.2.1 Mating force per EIA 364, Test #13	Measure force to mate at a rate of 13mm per minute max.	Maximum force: 0.54 N (55 grams contact) per	
5.2.2 Durability per EIA 364, Test # 09	Mate connectors up to 500 cycles at a maximum rate of 500 cycles per hour. When required Pre-conditioning to be done for 10 cycles at a rate of 500 cycles per hour.	Contact Resistand 10 milliohms Maxi Increase from Initi physical damage allowed	imum	
5.2.3 Mechanical Shock per EIA 364, Test # 27	30 g's peak acceleration half sine; 11 ms, 3 shocks applied along 3 mutually perpendicular planes, total 18 shocks.	Contact Resistand 10 milliohms Maxi Increase from Init Discontinuity: not than one microsed	imum ial; greater	
5.2.4 Vibration per EIA 364, Test # 28	Amplitude: 4.44 g's RMS. Sweep: 20-500 Hz random Duration: 20 minutes	Contact Resistand 10 milliohms Maxi Increase from Init Discontinuity: not than one microsed	imum ial; greater	
5.2.5 Unmating force per EIA 364, Test # 13	Measure force to unmate at a rate of 13mm per minute max.	.15N (15 g) minim contact		
5.2.6 Solderability per EIA 364, Test # 52	Category 1, no steam age; RMA class 1 flux immerse in molten solder at a temperature of 245 °C at a rate of 25.4 mm per sec. Hold in solder for 5 +/5 sec.	Solderable area s have a minimum o solder coverage		
5.2.7 Receptacle terminal retention	Measure force to extract terminal from plastic	0.5 Kg min. extrac force	ction	
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5.2 MECHANICAL PERFORMANCE (Cont'd)

Item	Test Condition	Requirement
5.2.8 Threaded insert push-out	Apply force at a rate of 13mm/min. max. until insert moves 0.50mm	3.0 Kg min. pushout force
5.2.9 Threaded insert Torque-out	Apply maximum recommended tightening torque to screwlocks the have been started into the threaded inserts	.34 Nm with no damage to inserts or housing
5.2.10 Boardlock Insertion force	Apply force to connector at a rate of 13mm/min. max. rate. Measure force to insert boardlock pc board. Hole diameter = 1.20±.08mm	5.1 Kg max/connector
5.2.11 Boardlock Withdrawal force	Measure force required to remove boardlock pc board. Hole diameter = 1.20± .08 mm Pull at a rate of 13mm/min. max. rate.	.50 Kg min. max/connector
5.2.12 Boardlock Retention to housing (73776 Housing)	Apply force at a rate of 13mm/min. max. rate. Measure force to extract boardlock from housing.	2.0 Kg min.

5.3 ENVIRONMENTAL PERFORMANCE:

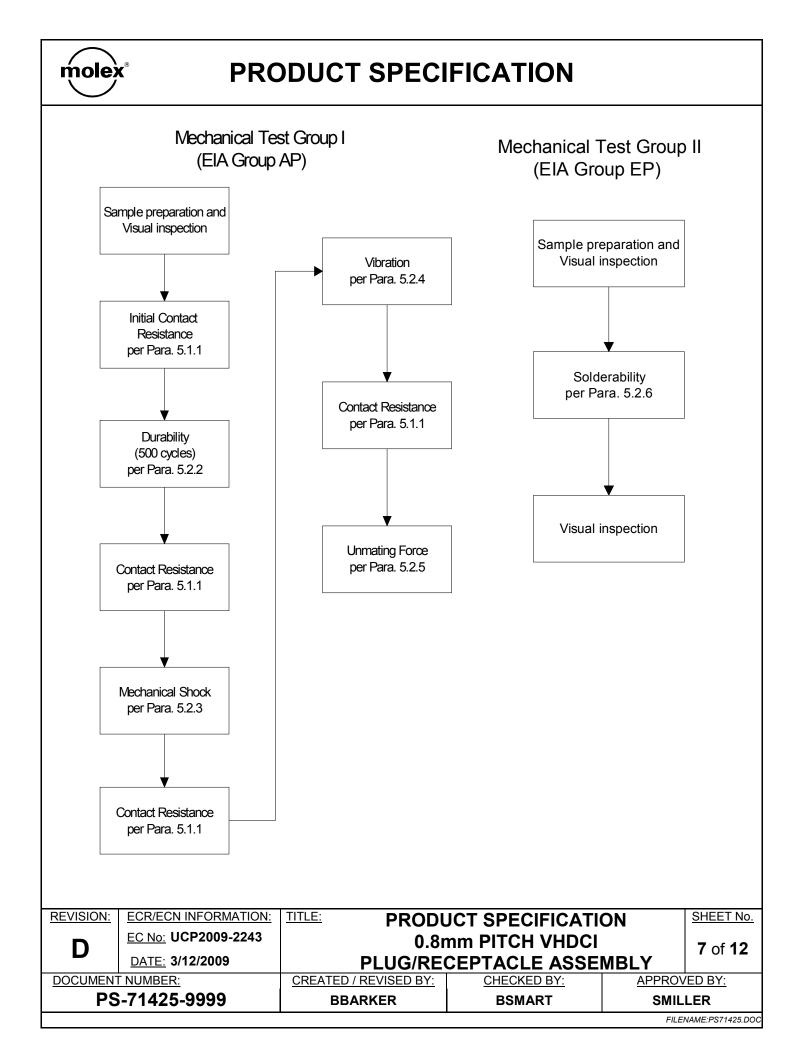
		ltem		Test Condition		Requirement]	
		5.3.1	Mated connectors exposed for 10 cycles (240 hours			Appe	arance: No		1
	Humi	dity-Temp	total) at 90-)-95% humidity and vary ter	mperature from	Dama	age Contact		
	cyclir	ng per EIA	25°C to 65°	5°C. Remove surface mois	ture and air dry	Resis	stance: 10		
	364,	Test #31	for 1 hour p	prior to measurements.		millio	hms Maximu	m	
						increa	ase from initia	al;	
						Insula	ation Resistar	nce:	
						500 N	/legohms Min	imum,	
						Diele	ctric Withstar	nding:	
						Volta	ge 250 VAC		
		5.3.2	Mated conr	nnectors exposed to 25 cycles –55°C to No physical dama		ge and			
	Therr	nal Shock	+85°C, half	If hour dwell, at externes. pass subse		subsequent t	ests.		
	per E	A 34, Test	10 mate/un	nmate precycles required (See 5.2.2)			act resistance		
		#32				-	hms Maximu		
						increa	ase from initia	al.	
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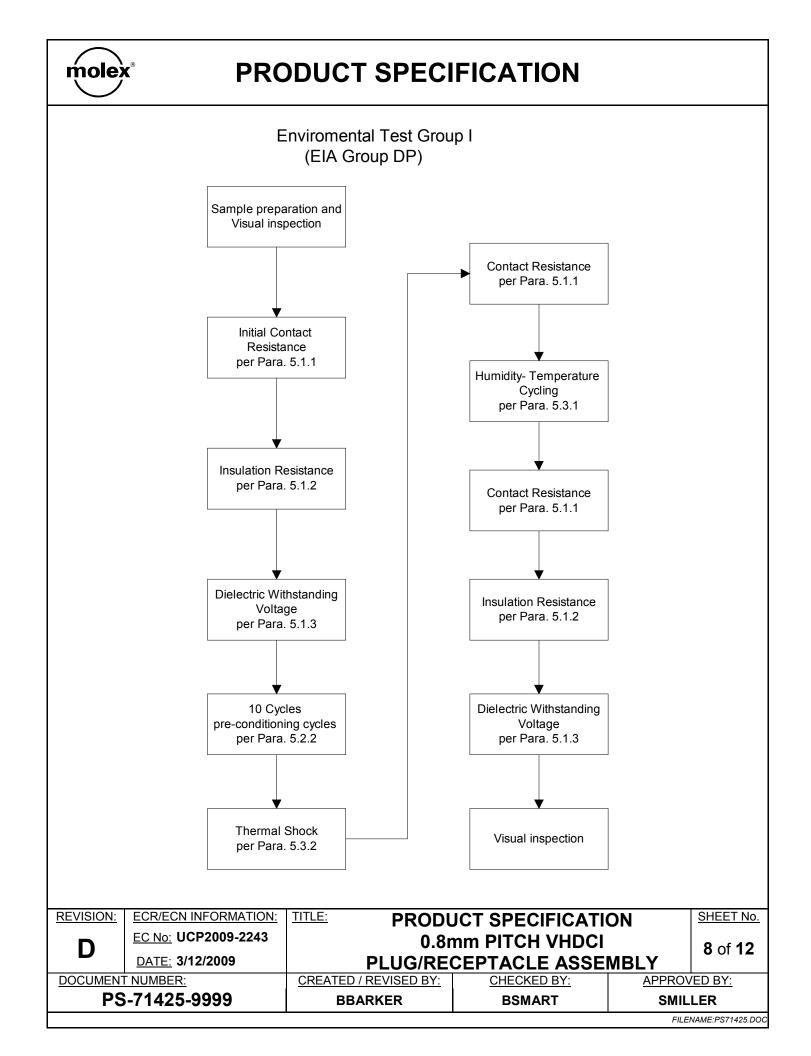


5.3 ENVIRONMENTAL PERFORMACE (Cont).

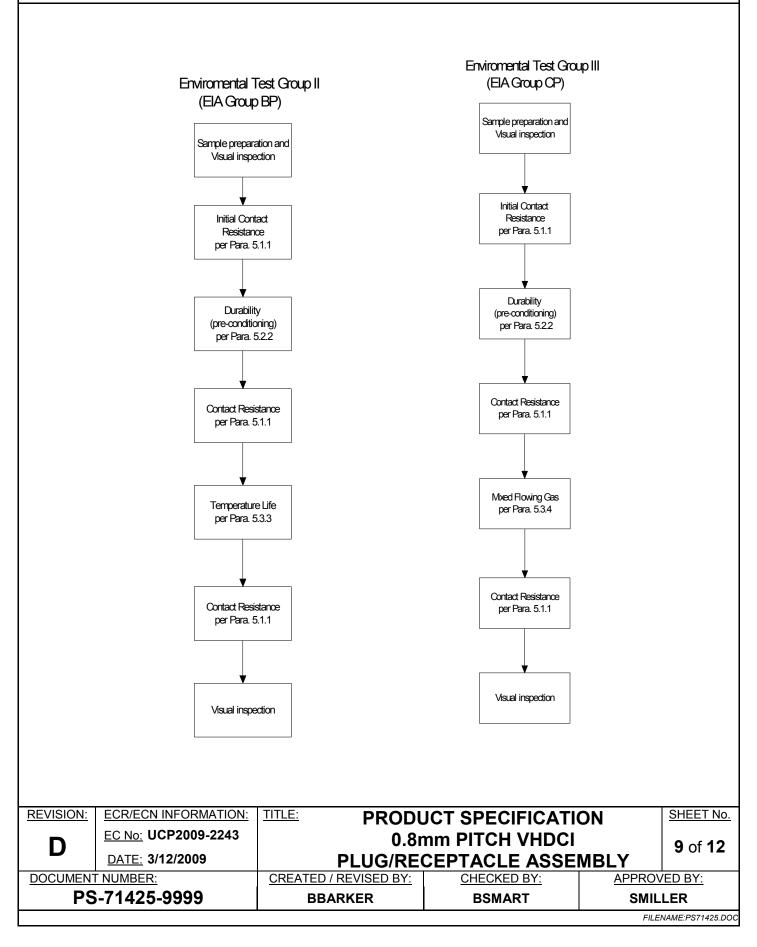
ltem	Test Condition	Requirement
5.3.3	+85°C for 500 hours	No physical damage and
Temperature Life		pass subsequent tests.
per EIA 364,		Contact Resistance: 10
Test #17		milliohms Maximum
		Increase from Initial.
5.3.4	Mated connector exposed to Class III for 20 days	No physical damage and
Flowing Mixed		pass subsequent tests.
Gas (FMG)		Contact Resistance: 10
per EIA 364,		milliohms Maximum
Test #65		Increase from Initial
5.3.5	Surface mount at 235°C +10°C, -0°C; all other	There shall be no
Resistance to	specimens at 260°C ±5°C	defects that would
soldering heat		impair normal
per EIA 364,		operations.
Test #56		
5.3.6	Trichloroethylene	There shall be no
Resistance to		defects that would
solvents		impair normal
per EIA 364,		operations.
Test #11		

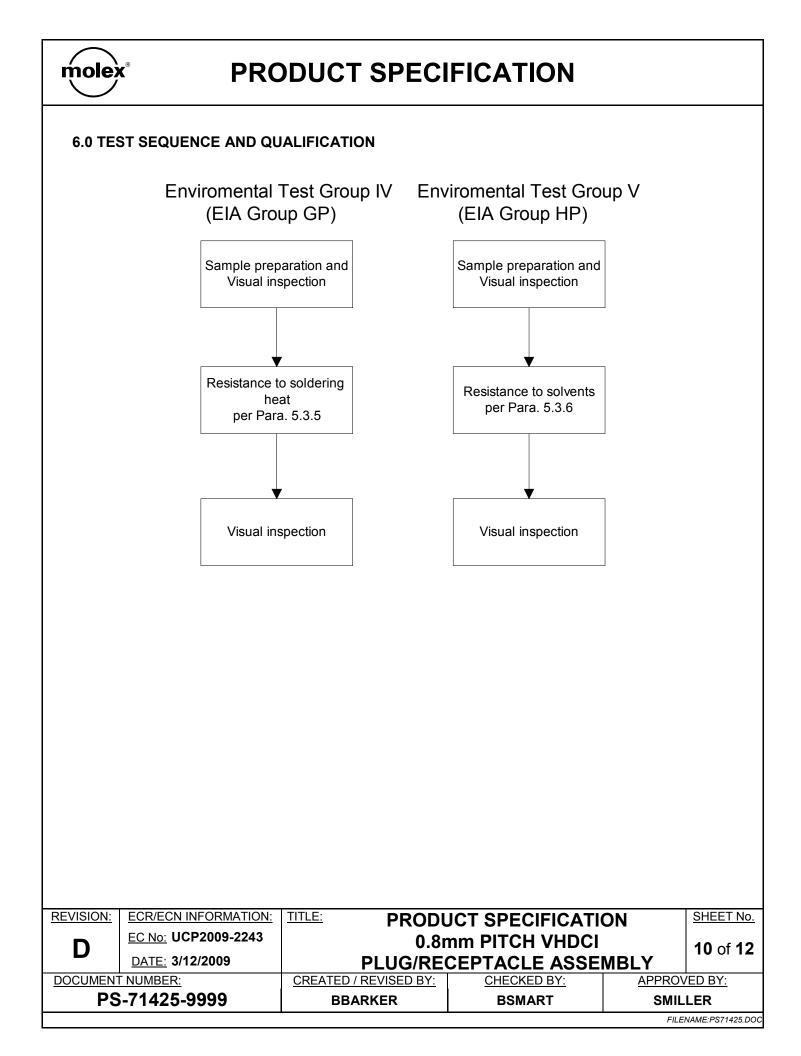
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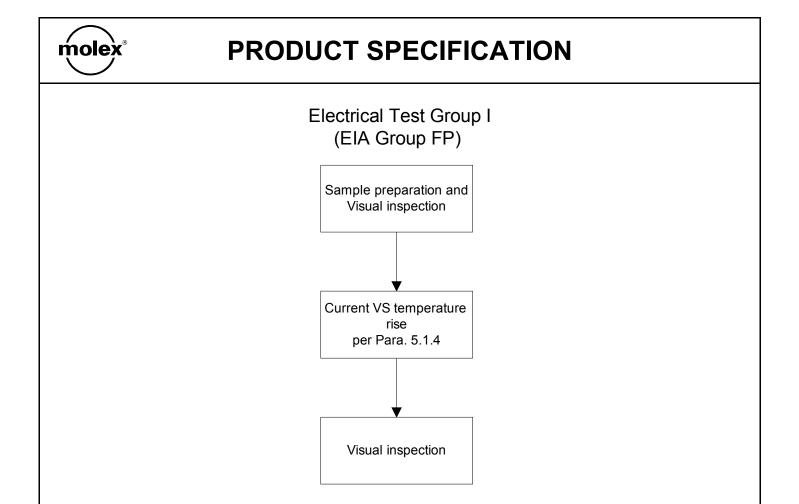












6.1 QUALIFICATION REQUIREMENT

- 6.1.1 Samples shall be taken from approved production processes.
- 6.1.2 The chart below specifies the number of samples required to be tested within each test group.
- 6.1.3 Acceptance criteria shall be as defined in the applicable test requirement in sections 5.1 5.3.

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7.0 PACKAGING

7.1 METHOD

7.1.1 Product shall be tray and tube packaged per the packaging specification as called out on the applicable assembly print.

7.2 REQUIREMENTS

7.2.1 Packaging shall meet the requirements and be tested per Molex specification PK-70180-5001.

8.0 MISCELLANEOUS

8.1 Test groups

Test group	Minimum number of samples	Permitted # of defects
Mechanical Test Group I	5 Assemblies	0
Mechanical Test Group II	5 Assemblies	0
Environmental Test Group I	15 Assemblies	0
Environmental Test Group II	15 Assemblies	0
Environmental Test Group III	15 Assemblies	0
Environmental Test Group IV	5 Assemblies	0
Environmental Test Group V	5 Assemblies	0
Electrical Test Group I	5 Assemblies	0

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